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TUFTY et al.(10) **Pub. No.: US 2023/0232524 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **LIQUID SUBMERSION COOLED
ELECTRONIC DEVICE WITH CLAMSHELL
ENCLOSURE**(71) Applicant: **LiquidCool Solutions, Inc.**, Rochester,
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(2013.01)(57) **ABSTRACT**

Liquid submersion cooled electronic devices and systems are described that use one or more cooling liquids, for example one or more dielectric cooling liquids, to submersion cool individual electronic devices or an array of electronic devices. A clamshell or sandwich construction of the device housing is used to define a wet zone containing heat producing electronic components of the electronic device to be cooled by the dielectric cooling liquid, and a dry zone where input/output and power connectors are provided.

